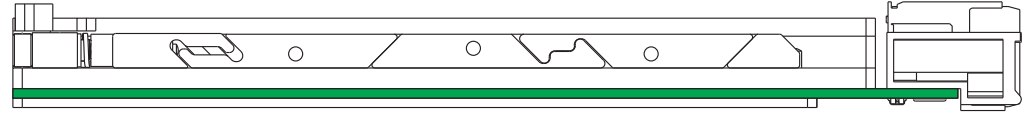


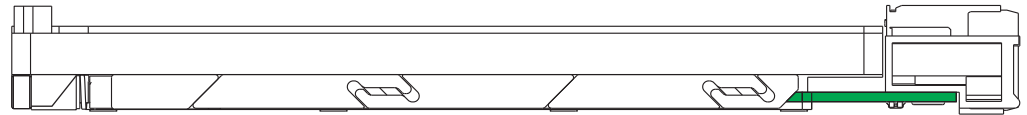
PRIMARY SIDE WEDGELOCK

- LOW POWER DESIGNS
- WEDGE LOCK IS ON TOP OF PCB
- PCB INCREASES THERMAL RESISTANCE TO COLD WALL
- PCB IN COLD WALL THERMAL PATH INCREASES RESISTANCE
- PCB PRIMARILY USED FOR CONVECTION ASSEMBLIES
- PCB INCLUDES IEEE CONVECTION FRONT PANEL HOLES
- THERMAL RESISTANCE TO COLDWALL $\sim 0.28 \text{ C}^\circ/\text{W}$



SECONDARY SIDE WEDGELOCK

- HIGH POWER DESIGNS
- WEDGE LOCK IS BESIDE PCB
- LOWEST THERMAL RESISTANCE TO COLD WALL
- PCB PRIMARILY USED FOR CONDUCTION DESIGNS
- PCB DOES NOT INCLUDE IEEE CONVECTION FRONT PANEL HOLES
- THERMAL RESISTANCE TO COLDWALL $\sim 0.05 \text{ C}^\circ/\text{W}$



PASS-THRU SOLIDWEDGE

- HIGH POWER DESIGNS
- SOLIDWEDGE PASSES BESIDE PCB
- LOW THERMAL RESISTANCE TO COLD WALL
- BOTH CONDUCTION AND CONVECTION DESIGNS
- PCB INCLUDES IEEE CONVECTION FRONT PANEL HOLES
- THERMAL RESISTANCE TO COLDWALL $\sim 0.09 \text{ C}^\circ/\text{W}$

